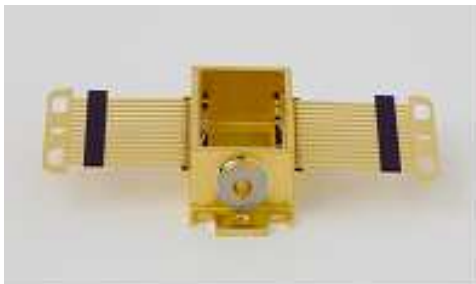


Description

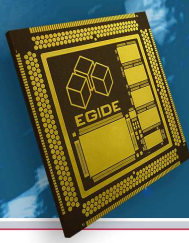
Egide's butterfly packages for telecom applications meet industry standard footprints and form factors. They are manufactured using either glass-to-metal seal or multilayer ceramic insert feedthru technology. Their high reliability and robustness make them ideally suited for telecom uses like high speed transmission lasers (CW, DM, EML or tuneable), pump lasers, as well as specific products such as SOA's and SLED's. Egide's assembly integration capabilities of a variety of components such as, thermal electric coolers, microwave connectors, tubes, and optics, combined with the flexible design will optimize your package's performance to your applications needs.



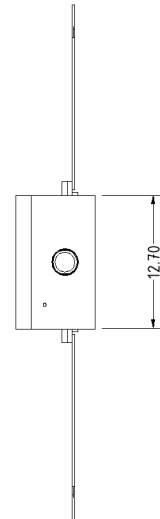
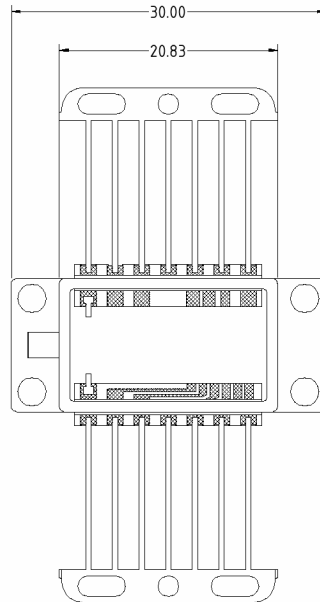
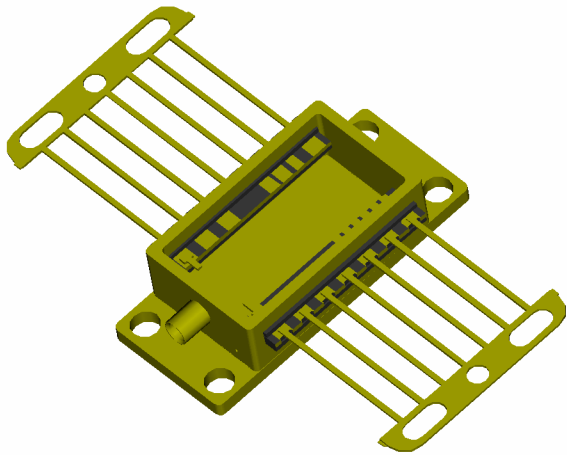
Features

- Hermeticity : 1×10^{-8} cc/s atm He
- Mechanical characteristics :
 - High or low profile
 - Kovar or CuW base for enhanced thermal conductivity
- Integration of other components using brazing and welding (TEC, sapphire, selfoc, ball lenses, tubes, ...)
- Microwave connector assembly (SMA, GPO, GPPO, ...)
- Lids also available
- CTMS or GTMS designs : 7, 14 or 26 pins
- Flexible, customizable designs with rapid turn around times

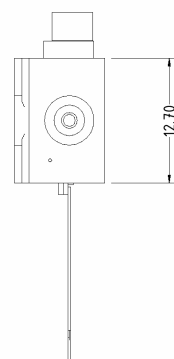
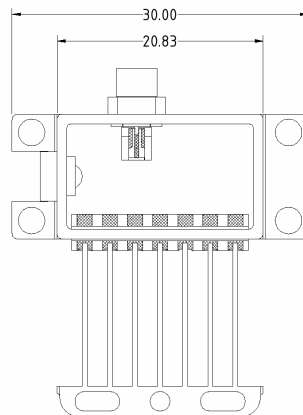
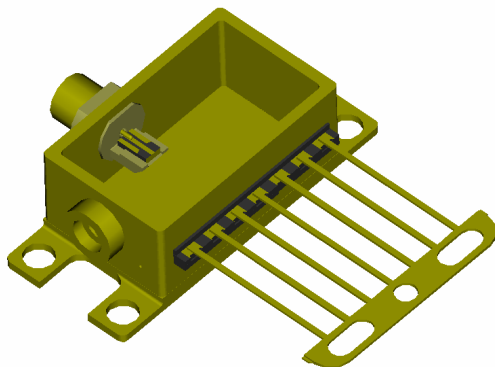
Contact : sales@egide.fr – sales@egideusa.com
www.egideusa.com - www.egide.fr



Package outline (examples)



Dimensions in mm



Dimensions in mm

Egide reserves the right to change specifications without prior notice

Contact : sales@egide.fr – sales@egideusa.com
www.egideusa.com - www.egide.fr